I hereby certify that this correspondence is being deposited in a first class mail envelope with the United States Postal Service addressed to: Commissioner for Patents, P.O. Alexandria, VA 22313. The applicant and/or attorney requests the date of deposit as the filing date.

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Date of Deposit: NOVEMBER 10, 2005 Depositor: ROBELT FABER NOV 18 2005

(Signature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of _____:

Cheng,et al. :

Group Art Unit: 2822

Serial No: 10/605,227

Examiner: Kiesha L. Rose

Filed: 9/16/03

International Business Machines Corporation

2070 Route 52

Hopewell Junction, NY 12533

TITLE:

STRUCTURE OF VERTICAL STRAINED SILICON DEVICES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the US and non-US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or nonpertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,

Cheng, et al.

Joseph P. Abate

Attorney for Applicant Registration No. 30.238

Telephone No. 845-894-4663

Fax No. 845-892-6363

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fis920030221 US.1 Fis920050192US4

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PORT PTO-1449 U.S. DEPARTMENT OF CONTROLS (REV. 7-80) PATENT AND TRADEMARK OFFICE	Atty. Docket No. FIS920030221US1	Serial No. 10/605,227					
CITED BY APPLICANT	Applicants Cheng, et al.						
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EXAMINER

DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

						
Form PTO-144 (RBV. 7-80)	9	U.S. DEPARTMENT OF COMPARENT AND TRADEMARK OF	GERCE OIPE	Atty. Docket No.		Serial No.
LIST OF PRIOR ART			FIS920030221US1		10/605,227	
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